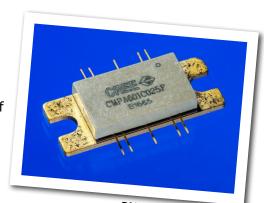


CMPA601C025F

25 W, 6.0 - 12.0 GHz, GaN MMIC, Power Amplifier

The CMPA601C025F GaN HEMT MMIC amplifier offers 25 Watts of power from 6 to 12 GHz of instantaneous bandwidth. The GaN HEMT MMIC is housed in a thermally-enhanced, 10 lead ceramic package. This delivers a high power 6 to 12GHz, high efficiency amplifier in a small footprint package at 50 ohms.



PN: CMPA601C025F Package Type: 440213

Typical Performance Over 6.0-12.0 GHz ($T_c = 25$ °c)

Parameter	6.0 GHz	7.5 GHz	9.0 GHz	10.5 GHz	12.0 GHz	Units
Small Signal Gain	35	34	34	37	31	dB
P_{OUT} @ P_{IN} = 22 dBm	42	45	43	41	34	W
Power Gain @ $P_{IN} = 22 \text{ dBm}$	22	23.5	23.5	23	22	dB
PAE @ P _{IN} = 22 dBm	27	39	31	33	25	%

Note: All data CW.

Features

- 33 dB Small Signal Gain
- 35 W Typical P_{SAT}
- Operation up to 28 V
- High Breakdown Voltage
- High Temperature Operation
- Size 0.172 x 0.239 x 0.004 inches

Applications

- Jamming Amplifiers
- Test Equipment Amplifiers
- Broadband Amplifiers



Absolute Maximum Ratings (not simultaneous) at 25°C

Parameter	Symbol	Rating	Units	Conditions
Drain-source Voltage	$V_{\scriptscriptstyle DS}$	84	V _{DC}	25°C
Gate-source Voltage	$V_{\sf GS}$	-10, +2	V _{DC}	25°C
Storage Temperature	T_{STG}	-40, +150	°C	
Operating Junction Temperature	T _j	225	°C	
Maximum Forward Gate Current	I_{GMAX}	23	mA	25°C
Soldering Temperature ¹	T _{STG}	245	°C	
Screw Torque	T	40	in-oz	
Thermal Resistance, Junction to Case ²	$R_{_{\thetaJC}}$	0.85	°C/W	85°C @ P _{DISS} = 116 W
Case Operating Temperature ²	T _c	-40, +150	°C	

Note¹ Refer to the Application Note on soldering at http://www.cree.com/rf/document-library

Note² See also, the Power Dissipation De-rating Curve on page 4

Electrical Characteristics (Frequency = 6.0 GHz to 12.0 GHz unless otherwise stated; $T_c = 25 \,^{\circ}\text{C}$)

Characteristics	Symbol	Min.	Тур.	Max.	Units	Conditions
DC Characteristics ^{1,2}						
Gate Threshold	V_{TH}	-3.8	-2.8	-2.3	V	V_{DS} = 10 V, I_{D} = 23 mA
Saturated Drain Current	\mathbf{I}_{DS}	10.6	13.0	-	Α	$V_{DS} = 6V$, $V_{GS} = 2 V$
Drain-Source Breakdown Voltage	$V_{\scriptscriptstyle BD}$	84	100	-	V	V_{GS} = -8 V, I_{DS} = 23 mA
RF Characteristics ³						
Small Signal Gain	S21	-	33	-	dB	V_{DD} = 28 V, I_{DQ} = 2 A, P_{IN} = -30 dBm
Output Power ^{3,4}	P _{OUT1}	-	46.2	-	dBm	$V_{_{\mathrm{DD}}}$ = 28 V, $I_{_{\mathrm{DQ}}}$ = 2 A, $P_{_{\mathrm{IN}}}$ = 22 dBm, Freq = 6 GHz
Output Power ^{3,4}	P _{OUT2}	-	46.3	-	dBm	V_{DD} = 28 V, I_{DQ} = 2 A, P_{IN} = 22 dBm, Freq = 9.5 GHz
Output Power ^{3,4}	P _{OUT3}	-	45.3	-	dBm	$V_{DD} = 28 \text{ V, } I_{DQ} = 2 \text{ A, } P_{IN} = 22 \text{ dBm, Freq} = 12 \text{ GHz}$
Power Added Efficiency ^{3,4}	PAE ₁	-	27	-	%	$V_{_{\mathrm{DD}}}$ = 28 V, $I_{_{\mathrm{DQ}}}$ = 2 A, $P_{_{\mathrm{IN}}}$ = 22 dBm, Freq = 6 GHz
Power Added Efficiency ^{3,4}	PAE ₂	-	31	-	%	$V_{DD} = 28 \text{ V, } I_{DQ} = 2 \text{ A, } P_{IN} = 22 \text{ dBm, Freq} = 9.5 \text{ GHz}$
Power Added Efficiency ^{3,4}	PAE ₃	-	24.5	-	%	V_{DD} = 28 V, I_{DQ} = 2 A, P_{IN} = 22 dBm, Freq = 12 GHz
Input Return Loss	S11	-	-5	-2.4	dB	$V_{_{DD}}$ = 28 V, $I_{_{DQ}}$ = 2 A, $P_{_{IN}}$ = -30 dBm
Output Return Loss	S22	-	-5	-2.1	dB	$V_{_{DD}}$ = 28 V, $I_{_{DQ}}$ = 2 A, $P_{_{IN}}$ = -30 dBm
Output Mismatch Stress	VSWR	-	5:1	VSWR	Ψ	No damage at all phase angles, $V_{DD} = 28 \text{ V}, I_{DQ} = 2 \text{ A}, P_{IN} = 22 \text{ dBm}$

Notes:

¹ Measured on-wafer prior to packaging.

² Scaled from PCM data.

³ Measured in CMPA601C025F-TB with 12.4 GHz low pass filter.

⁴ Fixture loss de-embedded using the following offsets. The offset is subtracted from the input offset value and added to the output offset value.

a) 6.0 GHz - 0.13 dB

b) 9.50 GHz - 0.26 dB

c) 12.0 GHz - 0.35 dB



CMPA601C025F Typical Performance

Figure 1. - Small Signal S-Parameters vs. Frequency $V_{DD} = 28 \text{ V}, I_{DO} = 2.0 \text{ A}, P_{IN} = -30 \text{ dBm}$

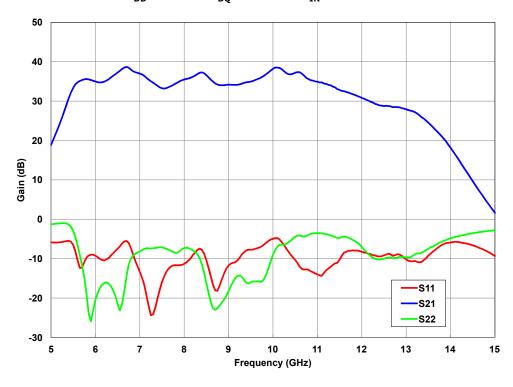
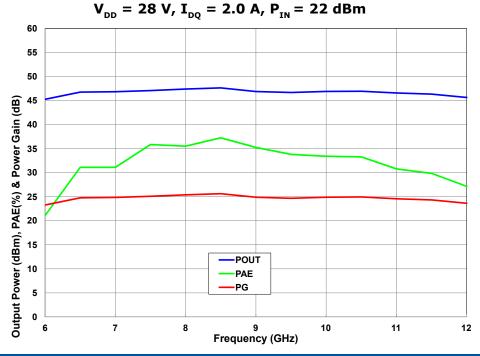


Figure 2. - Output Power, Gain and Power Added Efficiency vs. Input Power





CMPA601C025F Typical Performance

Figure 3. - Power Added Efficiency vs. Input Power $V_{DD} = 28 \text{ V}, I_{DO} = 2.0 \text{ A}$

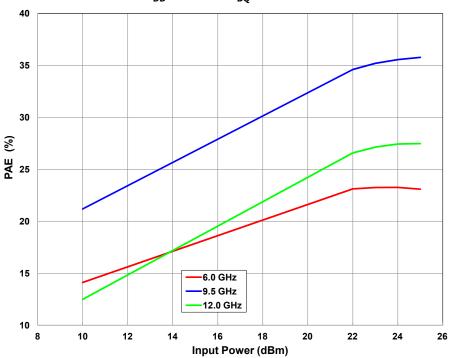
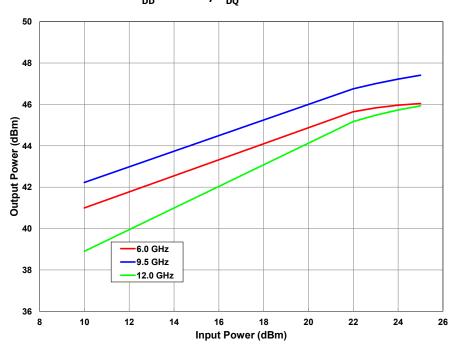


Figure 4. - Output Power vs. Input Power $V_{DD} = 28 \text{ V}, I_{DO} = 2.0 \text{ A}$



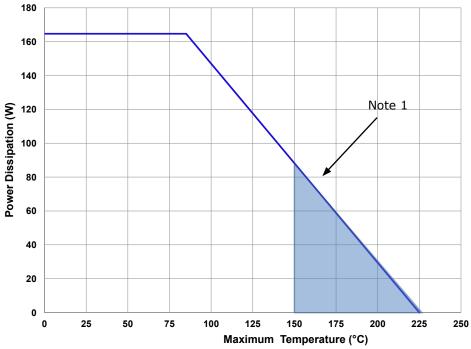


CMPA601C025F Typical Performance

Figure 5. - Gain vs Input Power $V_{_{\mathrm{DD}}}$ = 28 V, $I_{_{\mathrm{DQ}}}$ = 2.0 A 35 30 25 Power Gain (dB) 10 6.0 GHz 9.5 GHz 5 12.0 GHz 0 20 8 10 12 14 18 22 24 26

Figure 6. - Power Dissipation Derating Curve

Input Power (dBm)



Note 1. Area exceeds Maximum Case Operating Temperature (See Page 2).



CMPA601C025F-TB Demonstration Amplifier Circuit Bill of Materials

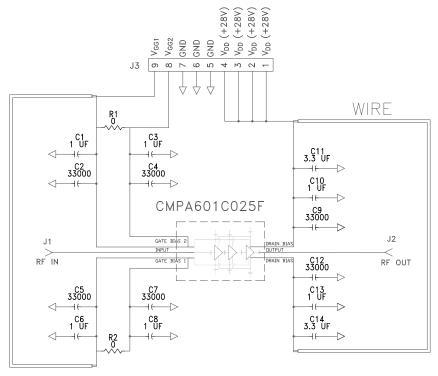
Designator	Description	Qty
C2,C4,C5,C7,C9,C12	CAP,33000PF, 0805,100V, X7R	6
C1,C3,C6,C8,C10,C13	CAP, 1.0UF, 100V, 10%, X7R, 1210	6
C11,C14	CAP ELECT 3.3UF 80V FK SMD	2
R1,R2	RES 0.0 OHM 1/16W 0402 SMD	2
J1,J2	CONN, SMA, PANEL MOUNT JACK, FLANGE, 4-HOLE, BLUNT POST, 20MIL	2
J3	HEADER RT>PLZ .1CEN LK 9POS	1
W1	WIRE, BLACK, 22 AWG ~ 1.50"	1
W2	WIRE, BLACK, 22 AWG ~ 1.75"	1
Q1	CMPA601C025F	1

CMPA601C025F-TB Demonstration Amplifier Circuit

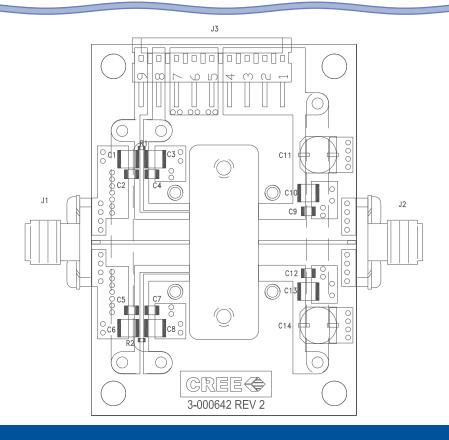




CMP601C025F-TB Demonstration Amplifier Circuit Schematic

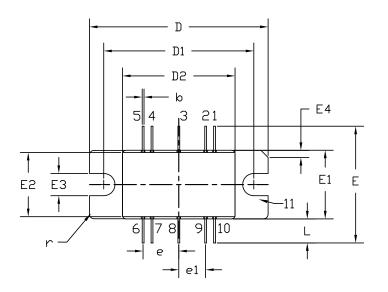


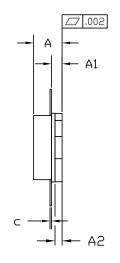
CMPA601C025F-TB Demonstration Amplifier Circuit Outline





Product Dimensions CMPA601C025F



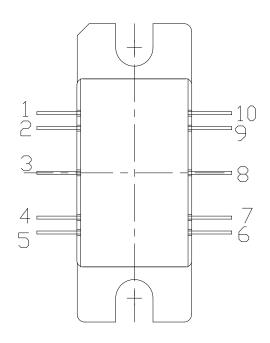


NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M -
- 2. CONTROLLING DIMENSION: INCH.
- 3. ADHESIVE FROM LID MAY EXTEND A MAXIMUM OF 0.020" BEYOND EDGE OF LID.
- 4. LID MAY BE MISALIGNED TO THE BODY OF PACKAGE BY A MAXIMUM OF 0.008' IN ANY DIRECTION.

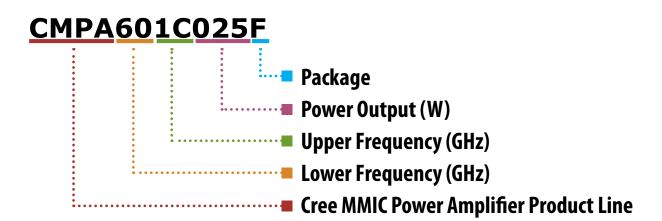
	INC	HES	MILLIM	IETERS	NOTES
DIM	MIN	MAX	MIN	MAX	
Α	0.155	0.175	3.94	4.45	
A1	0.055	0.065	1.40	1.65	
A2	0.035	0.045	0.89	1.14	
b	0.01	TYP	0.254 TYP		10x
С	0.007	0.009	0.18	0.23	
D	0.995	1.005	25.27	25.53	
D1	0.835	0.845	21.21	21.46	
D2	0.623	0.637	15.82	16.18	
E	0.653	0.653 TYP		TYP	
E1	0.380	0.390	9.65	9.91	
E2	0.355	0.365	9.02	9.27	
E3	0.120	0.130	3.05	3.30	
E4	0.035	0.045	0.89	1.14	45° CHAMFER
е	0.200 TYP		5.08 TYP		4x
e1	0.150) TYP	3.81	TYP	4x
L	0.115	0.155	2.92	3.94	10x
r	0.025 TYP		.635 TYP		3×

Pin Number	Qty
1	Gate Bias for Stage 1, 2 & 3
2	Gate Bias for Stage 1, 2 & 3
3	RF IN
4	Gate Bias for Stage 1, 2 & 3
5	Gate Bias for Stage 1, 2 & 3
6	Drain Bias
7	Drain Bias
8	RF OUT
9	Drain Bias
10	Drain Bias





Part Number System



Parameter	Value	Units	
Lower Frequency	6.0	GHz	
Upper Frequency ¹	12.0	GHz	
Power Output	25	W	
Package	Flanged	-	

Table 1.

Note¹: Alpha characters used in frequency code indicate a value greater than 9.9 GHz. See Table 2 for value.

Character Code	Code Value	
А	0	
В	1	
С	2	
D	3	
E	4	
F	5	
G	6	
Н	7	
J	8	
K	9	
Examples:	1A = 10.0 GHz 2H = 27.0 GHz	

Table 2.



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